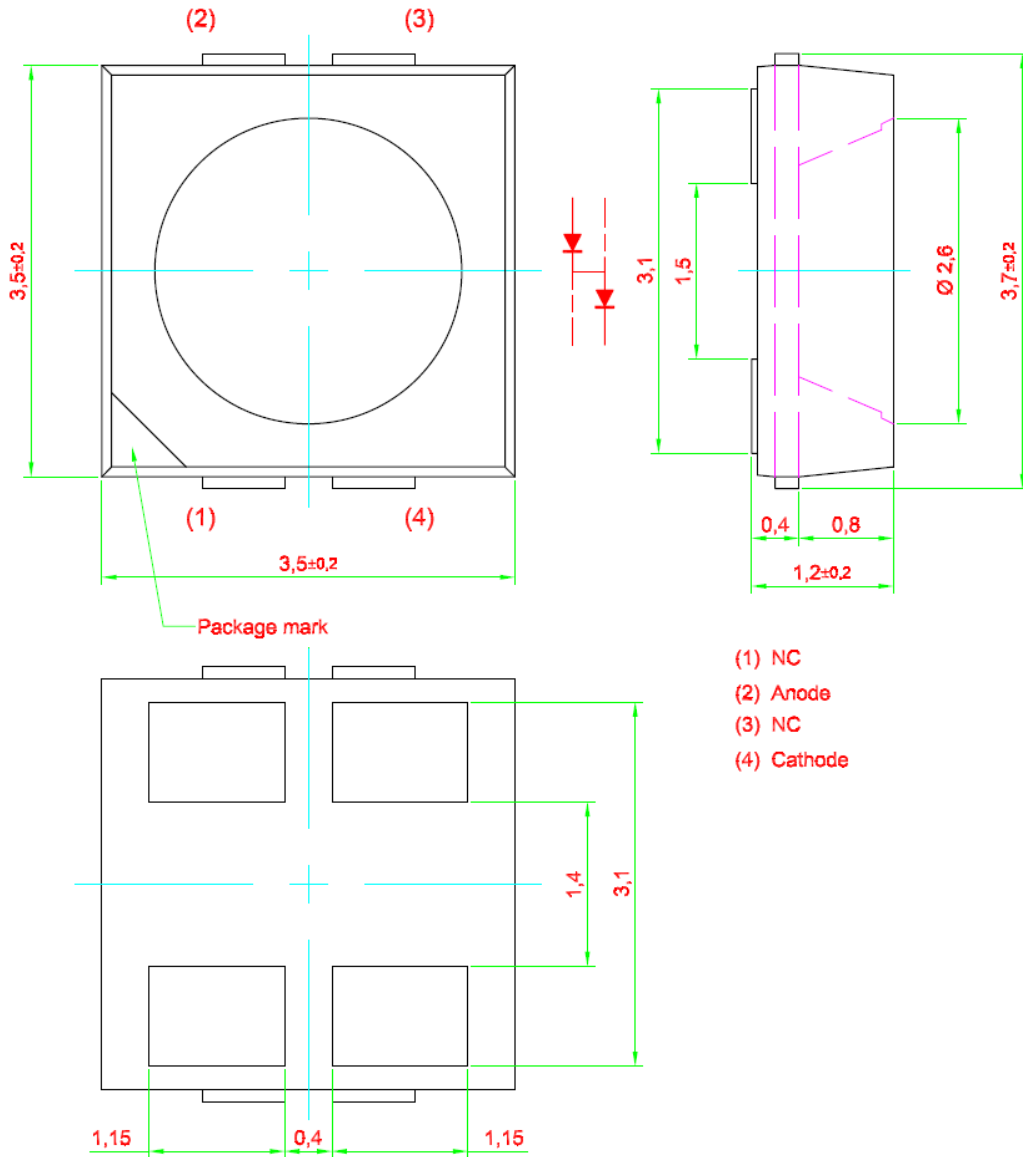


Engineering reference data are not verified. The specifications are subject to change without notice.

PrimaxBi 60 InGaN White: NCWW-ESG



- Super high brightness surface mount LED.
- 120° viewing angle.
- Compact package outline (LxW) of 3.5 x 3.5 mm. Ultra low height profile – 1.2 mm.
- Low thermal resistance.
- Compatible to IR reflow soldering.



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Material

	Material
Lead-frame.	Cu Alloy With Ag Plating.
Package.	High Temperature Resistant Plastic, PPA.
Encapsulant	Silicone Resin.
Soldering Leads.	Sn Plating.

Note: This product is Pb free.

Absolute Maximum Ratings

	Maximum Value	Unit
DC forward current per chip	70	mA
Peak pulse current per chip	120	mA
Reverse voltage.	10	V
LED junction temperature.	125	°C
Operating temperature.	-40 ... +100	°C
Storage temperature.	-40 ... +100	°C

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Optical Characteristics at Tj=25°C.

Part Number	Intensity @ If=60mA (mcd)			Viewing Angle
	Min	Typ.	Max	
NCWW-ESG-ABC-R	9000	11,000	14000	120

IV Bin	Intensity @ If = 60mA (mcd)		Flux @ If = 60mA
	Min	Max	Typical
AB	9000	11250	25.9
AC	11250	14000	32.2

1. Luminous intensity is measured with an accuracy of $\pm 11\%$.
2. Wavelength binning is carried for all units as per the wavelength-binning table. Only one wavelength group is allowed for each reel.

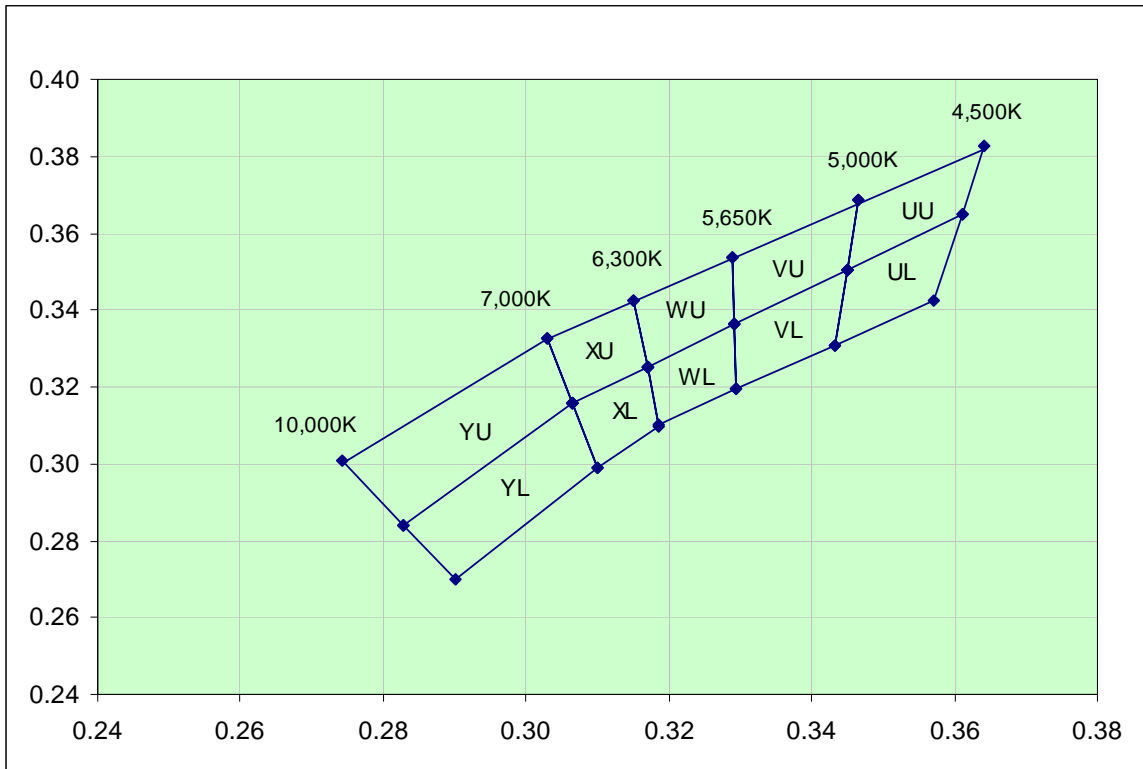
Electrical Characteristics at Tj=25°C.

Part Number	Vf @ If = 60mA / chip		
	Min. (V)	Typ. (V)	Max.(V)
NCWW-ESG	5.8	6.2	7.0

Forward voltages are tested using a current pulse of 1 ms and has an accuracy of $\pm 0.1V$.

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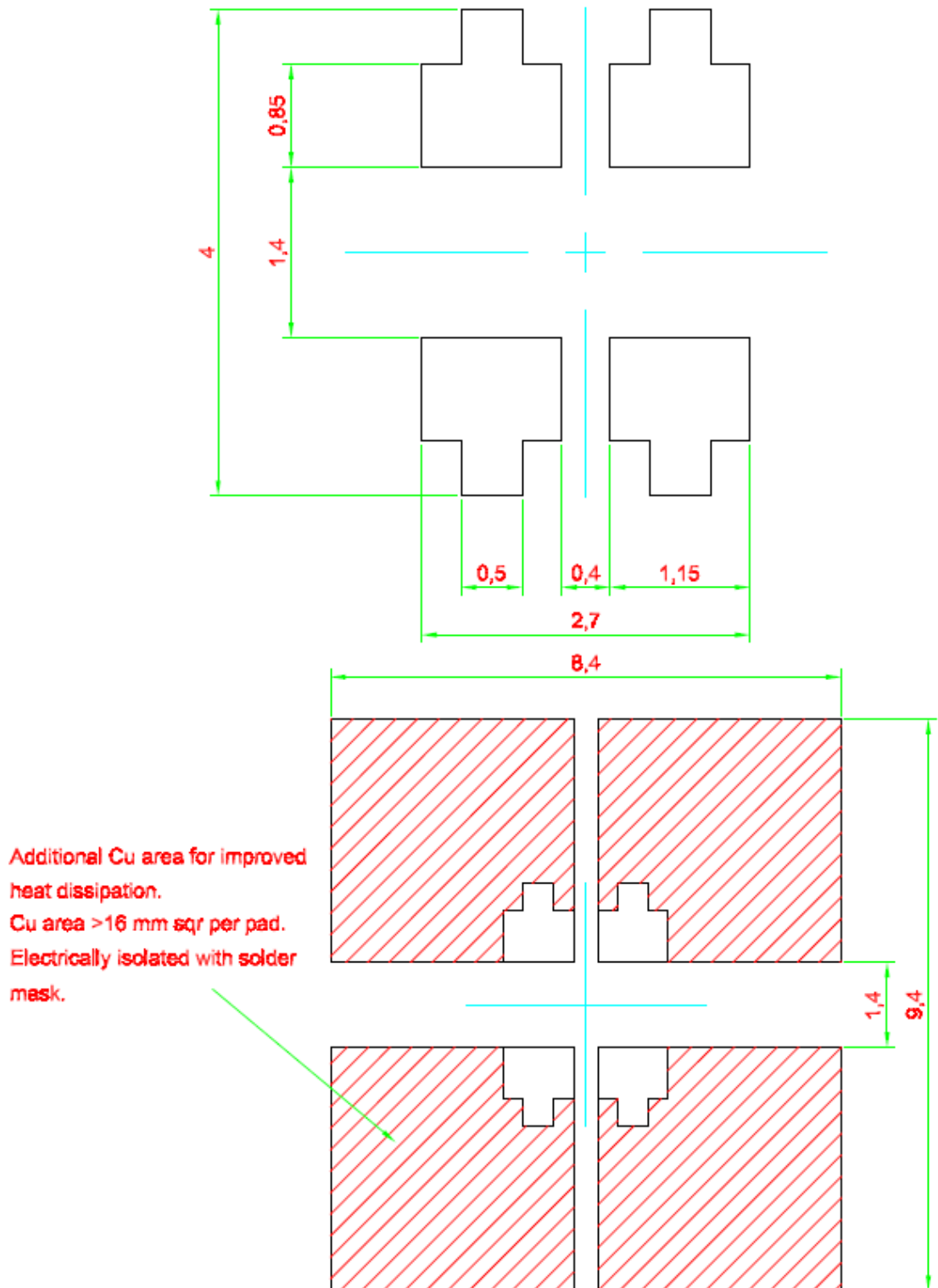
Color.



Bin		1	2	3	4
YU	Cx	0.274	0.283	0.307	0.303
	Cy	0.301	0.284	0.316	0.333
YL	Cx	0.283	0.290	0.310	0.307
	Cy	0.284	0.270	0.299	0.316
XU	Cx	0.303	0.307	0.317	0.315
	Cy	0.333	0.316	0.325	0.343
XL	Cx	0.307	0.310	0.319	0.317
	Cy	0.316	0.299	0.310	0.325
WU	Cx	0.315	0.317	0.329	0.329
	Cy	0.343	0.325	0.336	0.354
WL	Cx	0.317	0.319	0.329	0.329
	Cy	0.325	0.310	0.319	0.336
VU	Cx	0.329	0.329	0.345	0.347
	Cy	0.354	0.336	0.350	0.368
VL	Cx	0.329	0.329	0.343	0.345
	Cy	0.336	0.319	0.331	0.350
UU	Cx	0.347	0.345	0.361	0.364
	Cy	0.368	0.350	0.365	0.383
UL	Cx	0.345	0.343	0.357	0.361
	Cy	0.350	0.331	0.343	0.365

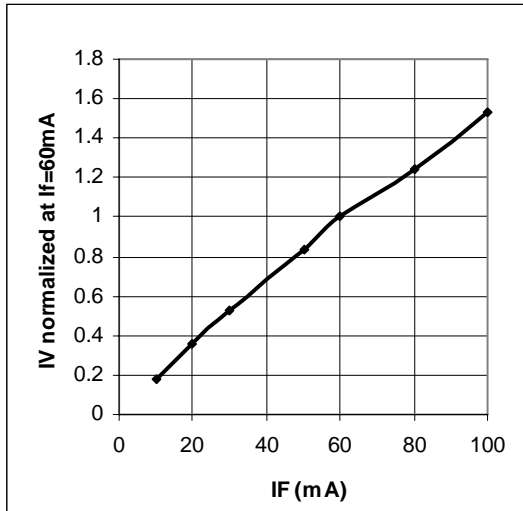
Engineering reference data are not verified. The specifications are subject to change without notice.

Solder Pad Design.

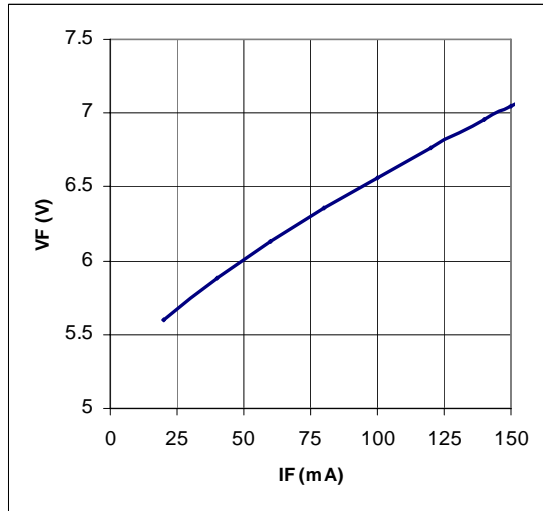


Engineering reference data are not verified. The specifications are subject to change without notice.

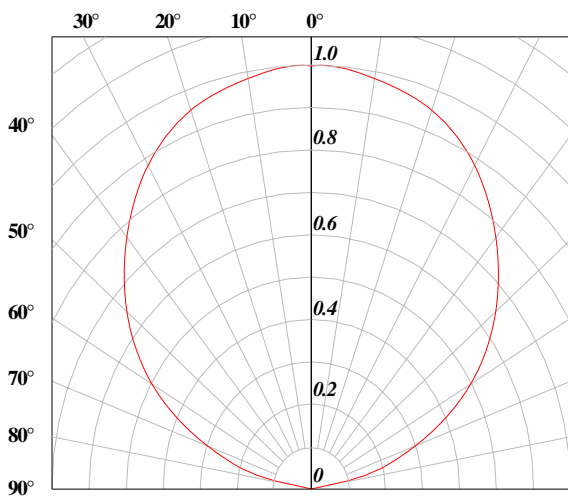
Relative intensity vs. forward current



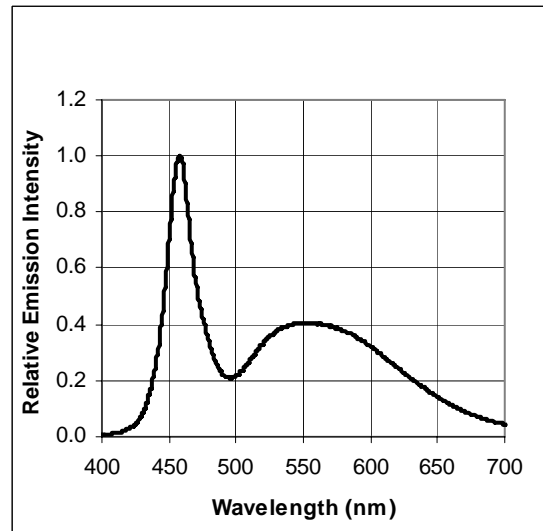
Forward voltage vs. forward current



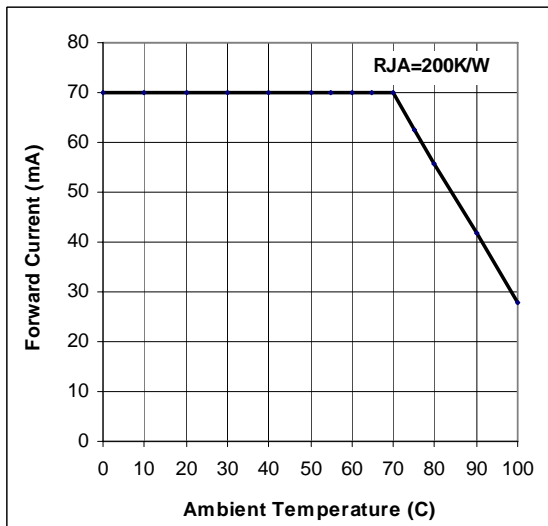
Radiation pattern.



Color Spectrum.



Max current vs. Ambient Temperature

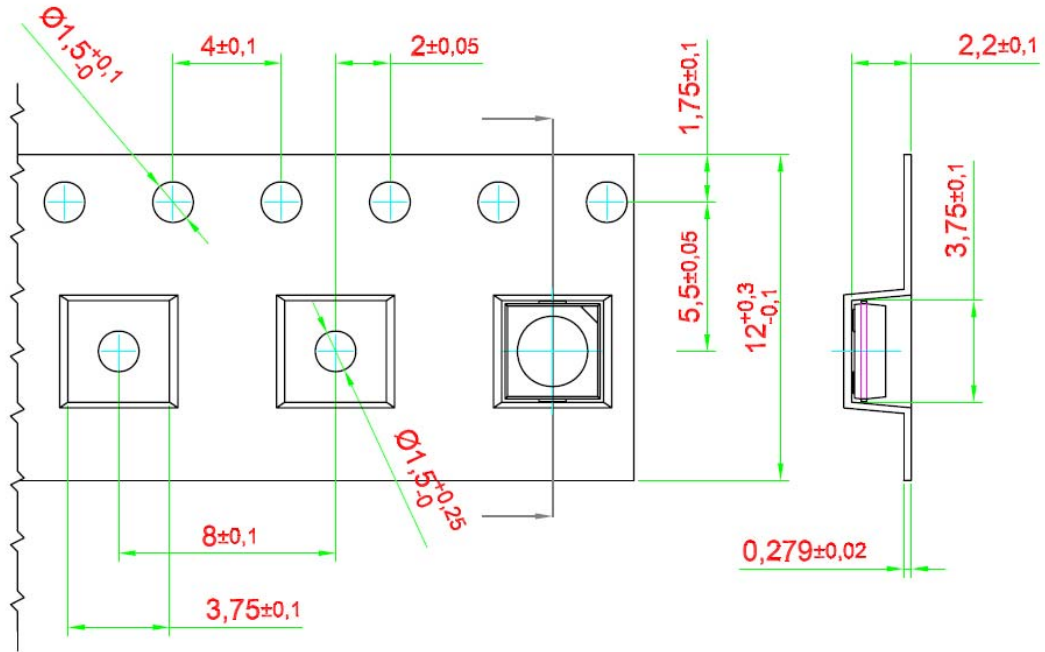


Engineering reference data are not verified. The specifications are subject to change without notice.

Taping And Orientation.

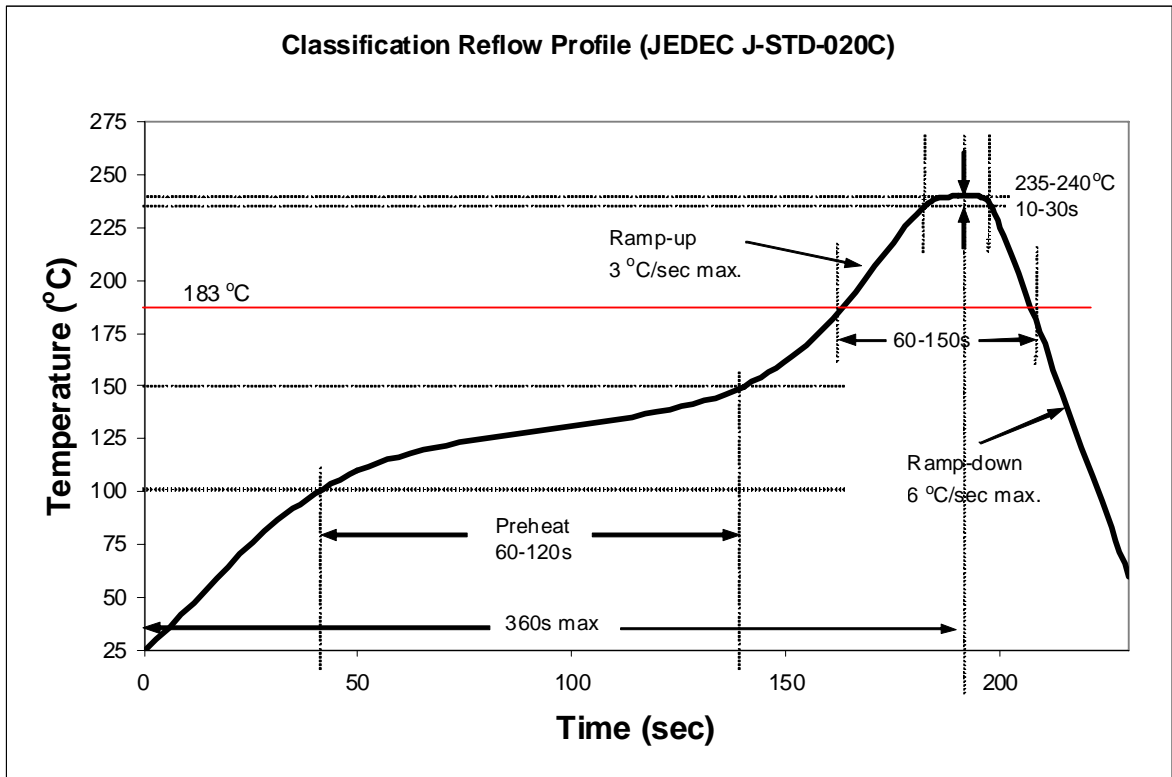
Reels come in quantity of 1000 units.

Reel diameters are 180 mm.

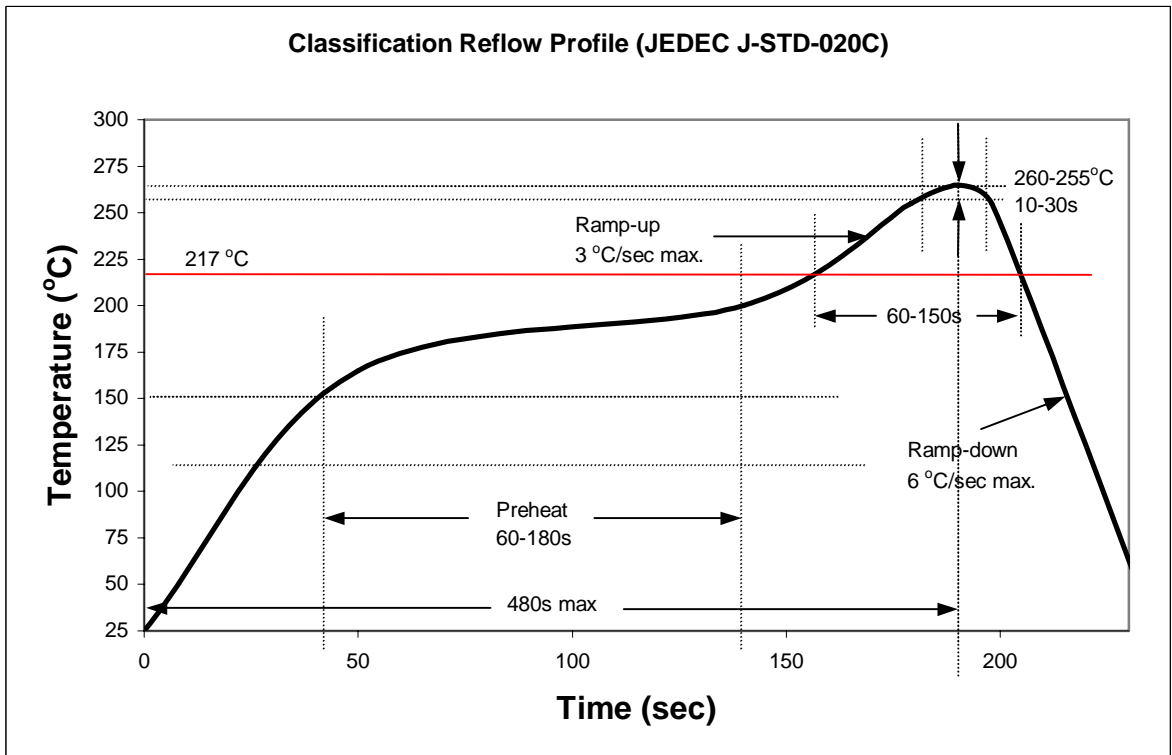


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Recommended Sn-Pb IR-Reflow Soldering Profile.



Recommended Pb Free IR-Reflow Soldering Profile.



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